

WHAT IS CLAIMED IS:

1. An electronic device comprising:  
an electronic element;  
a first external lead with an element placement pad having a thickness  $t$   
of less than 0.1 mm;  
and a second external lead that is disposed at a distance from said  
element placement pad,  
wherein said electronic element, element placement pad, part of said  
first external lead, and part of said second external lead are sealed with a  
sealing resin, said first external lead being bent in an S shape, the bending  
depth  $d$  thereof being at least as large as the thickness  $t$  of said first external  
lead, and the thickness  $T$  of said resin on a non-device side of said element  
placement pad being smaller than said bending depth  $d$ .
2. An electronic device according to claim 1, wherein the spacing between  
said element placement pad and said second external lead is no greater than  
0.12 mm.
3. An electronic device according to claim 1, wherein the vertical,  
horizontal, and height outer dimensions of said sealing resin are each no  
greater than 1.0 mm.
4. An electronic device according to claim 1, wherein widths of inner lead  
parts of said first and second external leads within said sealing resin are  
substantially uniform.
5. An electronic device according to claim 1, wherein the thickness of said  
electronic element is substantially the same as the thickness  $t$  of said first  
external lead.
6. An electronic device according to claim 1, wherein the sealing resin is  
injected from a position on a longer side of the sealing resin package, said  
position being offset toward one shorter side thereof.
7. An electronic device according to claim 1, wherein the bending radius  $R$   
on the outer surface of a bent part of said first external lead near the bottom

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surface of said sealing resin is at least 0.05 mm and is no greater than the lead thickness t.

8. An electronic device according to claim 1, wherein the sealing resin  
5 contains a filler, whose particle diameter is not greater than half the bending depth d of the said lead.

9. An electronic device comprising:  
an electronic element;  
10 a first external lead with an element placement pad having a thickness t of less than 0.1 mm; and a second external lead that is disposed at a distance from said element placement pad,  
wherein said electronic element, element placement pad, part of said  
15 first external lead, and part of said second external lead are sealed with a sealing resin, said first external lead and second external lead being bent at the bottom surface of said sealing resin, extending in a direction that is substantially parallel to said bottom surface of said sealing resin and being exposed, a depression being formed in the bottom surface part of said bent part  
20 of said first and second external leads, at which depressions the thicknesses of the leads are reduced, the bottom surfaces of said depressions of said first and second external leads and the bottom surface of said sealing resin being formed so as to be higher than the lowermost surfaces of the parts of said first and second external leads which extend outside.

10. An electronic device according to claim 9, wherein said depressions are  
25 formed within a projected boundaries of the sealing resin as seen from above.

11. An electronic device according to claim 9, wherein an escape part is  
30 formed at the bottom of the side of said sealing resin, the bottom edge position of said escape part being substantially the same as the formation position of said depression, and further wherein the distances from the boundary of a projected region as seen from above said sealing resin to said bottom edge position and said formation position are both no greater than the thickness of said lead.

12. An electronic device according to claim 9, wherein the lower surfaces of  
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